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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

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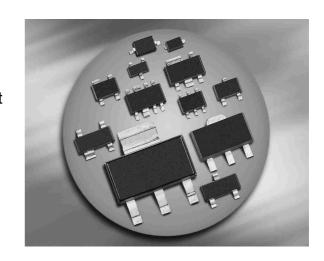




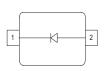
#### **Silicon Tuning Diode**

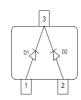
- High Q hyperabrupt tuning diode
- Designed for low tuning voltage operation for VCO's in mobile communications equipment
- High ratio at low reverse voltage
- Pb-free (RoHS compliant) package





BBY53-02L BBY53-02V BBY53-02W BBY53-03W **BBY53 BBY53-05W** 





Туре	Package	Configuration	<b>L</b> <sub>S</sub> (nH)	Marking	
BBY53	SOT23	common cathode	2	S7s	
BBY53-02L	TSLP-2-1	single, leadless	0.4	LL	
BBY53-02V	SC79	single	0.6	L	
BBY53-02W	SCD80	single	0.6	LL	
BBY53-03W	SOD323	single	1.8	white 5	
BBY53-05W	SOT323	common cathode	1.4	S7s	

## **Maximum Ratings** at $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage	$V_{R}$	6	V
Forward current	I <sub>F</sub>	20	mA
Operating temperature range	Top	-55 125	°C
Storage temperature	$T_{ m stg}$	-55 150	

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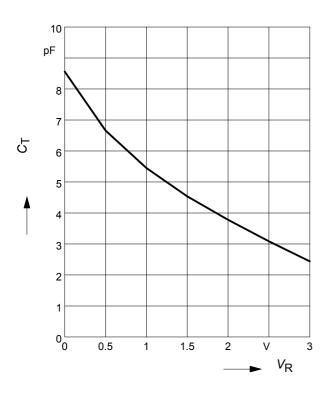
**Electrical Characteristics** at  $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol		Values		
	n		typ.	max.	
DC Characteristics	•	•			
Reverse current	$I_{R}$				nA
$V_{R}$ = 4 V		-	-	10	
$V_{R}$ = 4 V, $T_{A}$ = 85 °C		_	-	200	
AC Characteristics					
Diode capacitance	C <sub>T</sub>				pF
$V_{R} = 1 \text{ V}, f = 1 \text{ MHz}$		4.8	5.3	5.8	
$V_{R} = 3 \text{ V}, f = 1 \text{ MHz}$		1.85	2.4	3.1	
Capacitance ratio	C <sub>T1</sub> /C <sub>T3</sub>	1.8	2.2	2.6	-
$V_{R}$ = 1 V, $V_{R}$ = 3 V, $f$ = 1 MHz					
Series resistance	$r_{\rm S}$	-	0.47	-	Ω
$V_{R} = 1 \text{ V}, f = 1 \text{ GHz}$					



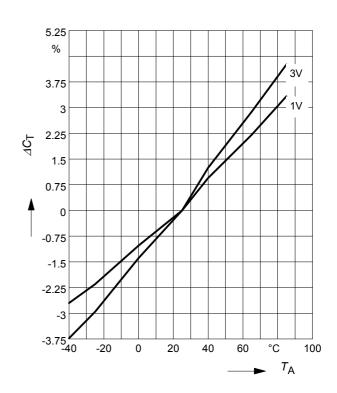
## **Diode capacitance** $C_T = f(V_R)$

f = 1MHz



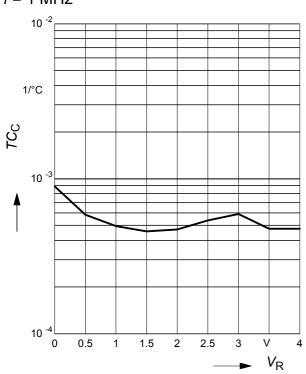
## Capacitance change $\Delta C = f(T_A)$

f = 1 MHz



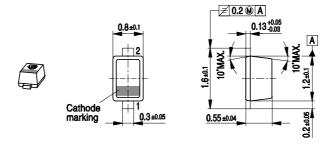
# Temperature coefficient of the diode capacitance $TC_C = f(V_R)$

f = 1 MHz



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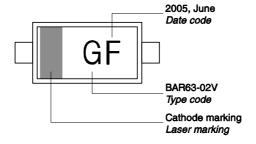




#### **Foot Print**



## Marking Layout (Example)

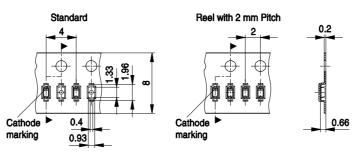


## Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel

Reel ø180 mm = 8.000 Pieces/Reel (2 mm Pitch)

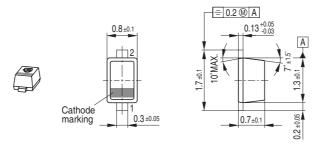
Reel ø330 mm = 10.000 Pieces/Reel







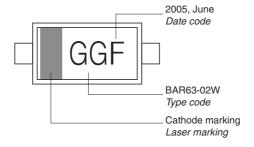




#### Foot Print



#### Marking Layout (Example)

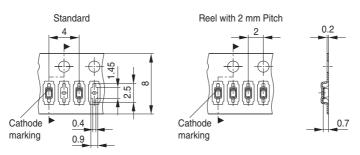


## Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel

Reel ø180 mm = 8.000 Pieces/Reel (2 mm Pitch)

Reel ø330 mm = 10.000 Pieces/Reel





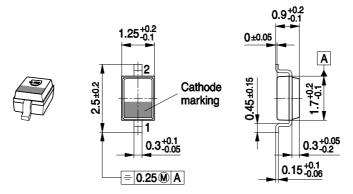
## Date Code marking for discrete packages with one digit (SCD80, SC79, SC751) CES-Code

Month	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014
01	а	р	Α	Р	а	р	Α	Р	а	р	Α	Р
02	b	q	В	Q	b	q	В	Q	b	q	В	Q
03	С	r	С	R	С	r	С	R	С	r	С	R
04	d	S	D	S	d	S	D	S	d	S	D	S
05	е	t	Е	T	е	t	Е	T	е	t	Е	Т
06	f	u	F	U	f	u	F	U	f	u	F	U
07	g	٧	G	٧	g	٧	G	٧	g	٧	G	V
08	h	Х	Η	Х	h	Х	Η	Χ	h	Х	Ι	X
09	j	у	7	Υ	j	у	7	Υ	j	у	7	Υ
10	k	Z	K	Z	k	Z	K	Z	k	Z	K	Z
11	I	2	L	4	I	2	L	4	I	2	L	4
12	n	3	Ν	5	n	3	Ν	5	n	3	Ζ	5

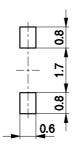
<sup>1)</sup> New Marking Layout for SC75, implemented at October 2005.

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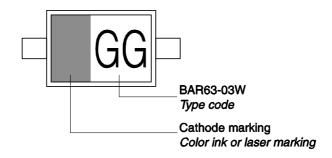




#### **Foot Print**

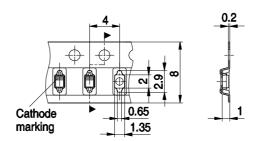


## Marking Layout (Example)

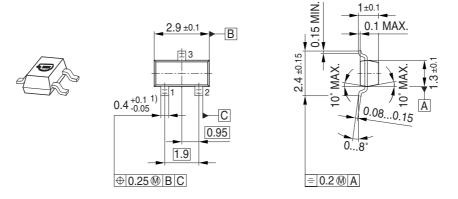


## Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel

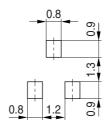




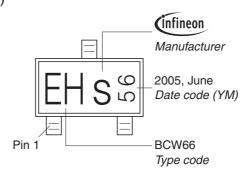


1) Lead width can be 0.6 max. in dambar area

Foot Print

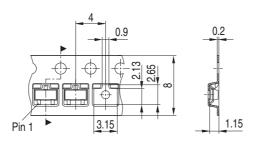


## Marking Layout (Example)



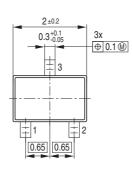
## Standard Packing

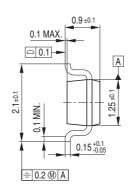
Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel



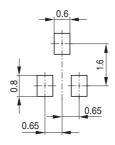




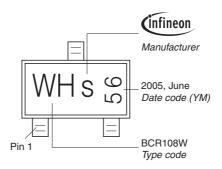




#### Foot Print

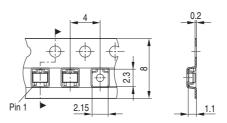


## Marking Layout (Example)

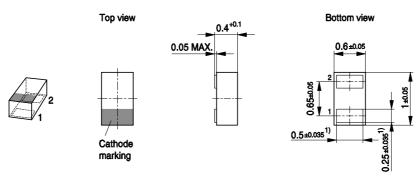


## Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel



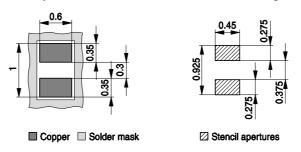




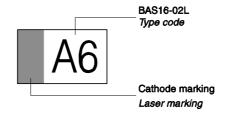
1) Dimension applies to plated terminal

#### **Foot Print**

For board assembly information please refer to Infineon website "Packages"

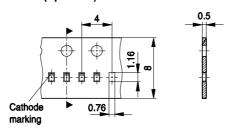


## Marking Layout (Example)



#### Standard Packing

Reel ø180 mm = 15.000 Pieces/Reel Reel ø330 mm = 50.000 Pieces/Reel (optional)





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